4 THICK FILM POLYMER PASTES

4.1 CONDUCTIVE RESIN PASTES

	C-1630	**C-1008**
Ag content（%）	70	65
Viscosity (Kcps) **SC 4-14 25℃ 10rpm**	15-30	80~150
Resistivity（m ohm /□ ）	≤30	≤150
Curing Thickness（μm）	10-25	20~25
Adhesion(N) ^{2x2mm}	Good	Good
Curing Temperature (℃)	150 - 180	200
Thinner	V-100	

4.2 RESISTANCE RESIN PASTES

R-5800* series	**Resistivity (ohm /□)**	**Tolerance（%）**	**TCR (ppm/℃)**	**Curing Temperature (℃)**	**Viscosity (Kcps)**
R-5811	10	±30	±800	130	30 - 130
R-5821	20				
R-5851	50				
R-5812	100				
R-5852	500				
R-5813	1K				
R-5814	10K				
R-5854	50K				
R-5815	100K				
**** R-5800E is for flexible substrate; Curing Temperature: 180 ℃***					

4.3 DIELECTRIC RESIN PASTES

	I-1821	**I-1823**	**I-1835**	**I-1835G**	**I-1830**
Color	Black	White	Blue	Green	Black
Viscosity **HBT SC4-14 25 ℃ 10 rpm**	80~150Kcps				
Print Screen Mech	200~325 mesh				
Drying	100~150℃、10~15min				
Curing	200~220℃、30min~80min				
Curing film thickness	20~50 μ m				
Thinner	V-1 V-252				V-0
Storage	0~10℃				